

Overview of index of products and services

1	Materials	4	Inspection and test systems
2	Manufacturing processes	5	Devices
3	Electronics assembly and packaging, system integration	6	Applications
		7	Services

Index of products and services

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|---|--|
| <p>1 Materials</p> <p>1.1 Substrates</p> <p><input type="checkbox"/> 1.1.1 Plastic films</p> <p><input type="checkbox"/> 1.1.2 Metal foils</p> <p><input type="checkbox"/> 1.1.3 Paper</p> <p><input type="checkbox"/> 1.1.4 Glass</p> <p><input type="checkbox"/> 1.1.5 Textiles</p> <p><input type="checkbox"/> 1.1.6 Other substrates</p> <p>1.2 Conductors</p> <p><input type="checkbox"/> 1.2.1 Organic conductors</p> <p><input type="checkbox"/> 1.2.2 Inorganic conductors</p> <p><input type="checkbox"/> 1.2.3 Nano materials</p> <p><input type="checkbox"/> 1.2.4 Carbon nanotubes</p> <p><input type="checkbox"/> 1.2.5 Graphene</p> <p><input type="checkbox"/> 1.2.6 Hybrid conductors</p> <p>1.3 Semiconductors</p> <p><input type="checkbox"/> 1.3.1 Polymer semiconductors</p> <p><input type="checkbox"/> 1.3.2 Small molecule semiconductors</p> <p><input type="checkbox"/> 1.3.3 Inorganic semiconductors</p> <p><input type="checkbox"/> 1.3.4 Nano materials semiconductors</p> <p><input type="checkbox"/> 1.3.5 Carbon nanotube semiconductors</p> <p><input type="checkbox"/> 1.3.6 Hybrid semiconductors</p> <p>1.4 Dielectrics</p> <p><input type="checkbox"/> 1.4.1 Organic dielectrics</p> <p><input type="checkbox"/> 1.4.2 Inorganic dielectrics</p> <p><input type="checkbox"/> 1.4.3 Nano materials</p> <p><input type="checkbox"/> 1.4.4 Hybrid dielectrics</p> <p>1.5 Encapsulation materials, resins and adhesives</p> <p><input type="checkbox"/> 1.5.1 Thin film encapsulation</p> <p><input type="checkbox"/> 1.5.2 Polymer film encapsulation</p> <p><input type="checkbox"/> 1.5.3 Metal encapsulation</p> <p><input type="checkbox"/> 1.5.4 Glass encapsulation</p> <p><input type="checkbox"/> 1.5.5 Resins and adhesives</p> <p><input type="checkbox"/> 1.6 Other materials</p> <p>2 Manufacturing processes</p> <p>2.1 Mass patterning techniques</p> <p><input type="checkbox"/> 2.1.1 Gravure printing</p> <p><input type="checkbox"/> 2.1.2 Offset printing</p> <p><input type="checkbox"/> 2.1.3 Flexographic printing</p> <p><input type="checkbox"/> 2.1.4 Screen printing</p> <p><input type="checkbox"/> 2.1.5 Other mass patterning techniques</p> | <p>2.2 Digital printing</p> <p><input type="checkbox"/> 2.2.1 Ink-jet printing</p> <p><input type="checkbox"/> 2.2.2 Other digital printing</p> <p>2.3 Other printing processes</p> <p><input type="checkbox"/> 2.3.1 Microcontact printing</p> <p><input type="checkbox"/> 2.3.2 Nano imprint</p> <p>2.4 Vacuum processes</p> <p><input type="checkbox"/> 2.4.1 Evaporation</p> <p><input type="checkbox"/> 2.4.2 Sputtering</p> <p><input type="checkbox"/> 2.4.3 Organic vapor phase deposition (OVPD)</p> <p><input type="checkbox"/> 2.4.4 Other vacuum processes</p> <p><input type="checkbox"/> 2.5 Photolithography</p> <p>2.6 Laser processes</p> <p><input type="checkbox"/> 2.6.1 Laser ablation</p> <p><input type="checkbox"/> 2.6.2 Laser transfer</p> <p>2.7 Coating technologies</p> <p><input type="checkbox"/> 2.7.1 Spin coating</p> <p><input type="checkbox"/> 2.7.2 Dip coating</p> <p><input type="checkbox"/> 2.7.3 Blade coating</p> <p><input type="checkbox"/> 2.7.4 Other coating techniques</p> <p>2.8 Material processing</p> <p><input type="checkbox"/> 2.8.1 Dispersion technologies</p> <p><input type="checkbox"/> 2.8.2 Other material processing</p> <p>2.9 Light induced processing</p> <p><input type="checkbox"/> 2.9.1 IR drying</p> <p><input type="checkbox"/> 2.9.2 UV curing</p> <p><input type="checkbox"/> 2.9.3 Laser processes</p> <p>2.10 Dosing and mixing technology</p> <p><input type="checkbox"/> 2.10.1 Pumps</p> <p><input type="checkbox"/> 2.10.2 Other dosing and mixing technologies</p> <p>2.11 Encapsulation</p> <p><input type="checkbox"/> 2.11.1 Thin film encapsulation</p> <p><input type="checkbox"/> 2.11.2 Polymer film encapsulation</p> <p><input type="checkbox"/> 2.11.3 Metal encapsulation</p> <p><input type="checkbox"/> 2.11.4 Glass encapsulation</p> <p><input type="checkbox"/> 2.11.5 Other encapsulation processes</p> <p><input type="checkbox"/> 2.12 Clean room technology</p> <p><input type="checkbox"/> 2.13 Roll-to-roll processing</p> <p><input type="checkbox"/> 2.14 Other manufacturing processes</p> |
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Index of products and services

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3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
 - 3.1.1 Flip chip
 - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
- 4.3 Chemical characterization
- 4.4 Simulation/circuit optimization
- 4.5 Lifetime testing
- 4.6 Quality/process control
- 4.7 Environmental testing
- 4.8 Other inspection and test systems

5 Devices

- 5.1 Transistors
- 5.2 Diodes
- 5.3 Passive components
 - 5.3.1 Capacitors
 - 5.3.2 Resistors
 - 5.3.3 Other passives
- 5.4 Integrated circuits
- 5.5 Displays
 - 5.5.1 OLED
 - 5.5.2 Electrochromic displays
 - 5.5.3 Electrochromic displays
 - 5.5.4 Electroluminescent displays
 - 5.5.5 LCD
 - 5.5.6 Electrowetting
 - 5.5.7 Other displays
- 5.6 Photovoltaic cells
 - 5.6.1 Organic photovoltaics
 - 5.6.2 Hybrid photovoltaics
 - 5.6.3 Inorganic photovoltaics

5.7 Sensors

- 5.7.1 Photodiodes
- 5.7.2 Pressure sensors
- 5.7.3 Temperature sensors
- 5.7.4 Biomedical sensors
- 5.7.5 Gas sensors
- 5.7.6 Touch sensors
- 5.7.7 Other sensors
- 5.8 Memory elements
- 5.9 Antennas
- 5.10 Batteries
- 5.11 Components for hybrid systems
- 5.12 Other devices

6 Applications

- 6.1 TFT backplanes
- 6.2 Displays
- 6.3 Sensors
- 6.4 Smart systems
- 6.5 RFID
- 6.6 Solar cells
- 6.7 Smart textiles
- 6.8 Speakers
- 6.9 Lighting
- 6.10 Other applications

7 Services

- 7.1 Consulting
- 7.2 R&D funding program management
- 7.3 R&D/Research & Development
- 7.4 Prototyping
- 7.5 Manufacturing
- 7.6 Venture and equity capitalization
- 7.7 Professional and trade associations
- 7.8 Technical books, technical journals, technical publishers
- 7.9 Other services